

IN THE CLAIMS

Claim 1 (Currently Amended): A heat conductive silicone composition comprising

(a) 100 parts by weight of an organopolysiloxane having alkenyl groups only at both ends of a molecular chain,

(b) 200 to 3,000 parts by weight of a heat conductive filler,

(c) an organohydrogen polysiloxane component consisting of at least one organohydrogen polysiloxane having hydrogen atoms directly bonded to silicon atoms (Si-H groups) only at both ends of a molecular chain, in such an amount that 0.1 to 5 moles of Si-H groups are available per mole of alkenyl groups in component (a), and

(d) a platinum group base curing catalyst in an amount to give 0.1 to 500 ppm of platinum group element based on the weight of component (a),

wherein the compositions when cured is non-elastic and has a penetration of 10 to 200 according to JIS K2207.

Claim 2 (Original): The composition of claim 1 wherein the heat conductive filler is selected from the group consisting of metals, oxides, nitrides, silicides, artificial diamond and mixtures thereof.

Claim 3 (Original): A heat conductive silicone article obtained by shaping the composition of claim 1 into a sheet.

Claim 4 (Original): A heat conductive silicone article shaped by applying the composition of claim 1 onto a heat dissipating sheet.